TK13A60D



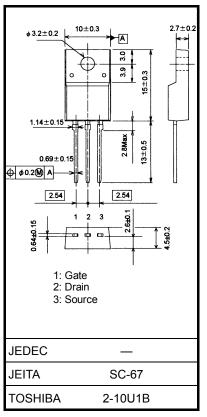
Switching Regulator Applications

Unit: mm

- Low drain-source ON-resistance: RDS (ON) = 0.33Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 6.5 \text{ S (typ.)}$
- Low leakage current: $I_{DSS} = 10 \mu A (V_{DS} = 600 \text{ V})$
- Enhancement mode: $V_{th} = 2.0 \text{ to } 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	600	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	13	Α	
	Pulse (t = 1 ms) (Note 1)	I _{DP}	52		
Drain power dissipati	on (Tc = 25°C)	P _D	50	W	
Single pulse avalanche energy (Note 2)		E _{AS}	511	mJ	
Avalanche current		I _{AR}	13	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	5.0	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55 to 150	°C	



Weight: 1.7 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

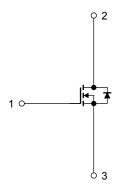
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.5	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 5.3 mH, R_G = 25 Ω , I_{AR} = 13 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.



Electrical Characteristics (Ta = 25°C)

Char	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±1	μА
Drain cut-off curr	ent	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V	_	_	10	μА
Drain-source bre	akdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	600	_	_	V
Gate threshold ve	oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	٧
Drain-source ON	-resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 6.5 A		0.33	0.43	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 6.5 A	1.8	6.5		S
Input capacitance		C _{iss}		_	2300	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	10	_	
Output capacitance		C _{oss}		_	250	_	
Switching time	Rise time	t _r	$\begin{array}{c c} 10 \text{ V} & \text{I}_D = 6.5 \text{ A} & \text{V}_{OUT} \\ \hline \text{VGS} & \text{O} & \text{V} & \text{EL} = \\ \hline 50 \Omega & \text{W}_{DD} \approx 200 \text{ V} \\ \\ \end{array}$ Duty \leq 1%, $t_W =$ 10 μs	_	50	_	
	Turn-on time	t _{on}		_	100	_	no
	Fall time	t _f			25		ns
	Turn-off time	t _{off}		_	140	_	
Total gate charge		Qg		_	40	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 13 \text{ A}$	_	25	_	nC
Gate-drain charge		Q _{gd}		_	15	_	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	13	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	52	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 13 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 13 A, V _{GS} = 0 V,	_	1600	_	ns
Reverse recovery charge	Q _{rr}	dI _{DR} /dt = 100 A/μs	_	20	_	μС

Marking

